&TDK Multilayer Ceramic Chip Capacitors

C1608C0G1H090C080AA



TDK item description C1608C0G1H090CT****

IDK item description C1608C0G1H090C1****		N/h
Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C1608 [EIA 0603]	6
Status	Production (Not Recommended for New Design)	Dimensions in mr

	Size
Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.80mm ±0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	9pF ±0.25pF	
Rated Voltage	50VDC	
Temperature Characteristic	C0G(0±30ppm/°C)	
Q (Min.)	580	
Insulation Resistance (Min.)	10000ΜΩ	

Other		
Coldering Method	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	4000pcs	

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Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



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Associated Images



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